

Schottky Barrier Diode Silicon Epitaxial Planar

JDH2S02SL

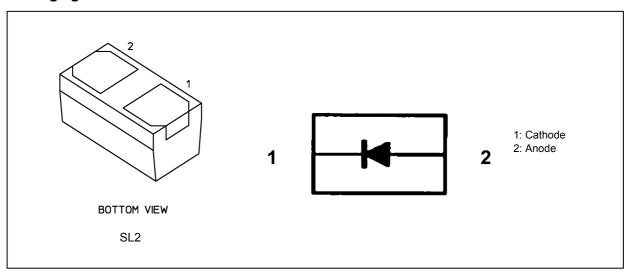
1. Applications

Radio-Frequency Power Detectors

2. Features

• Suitable for reducing the product size due to the use of a small two-pin package supporting high-density mounting

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) (Unless otherwise specified, Ta = 25 °C)

Characteristics	Symbol	Note	Rating	Unit
Reverse voltage	V _R		10	V
Forward current	I _F		10	mA
Junction temperature	Tj		125	°C
Storage temperature	T _{stg}		-55 to 125	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note: This device is sensitive to electrostatic discharge (ESD). Extreme ESD conditions should be using proper antistatic precautions for the worktable, operator, solder iron and so on.

Start of commercial production

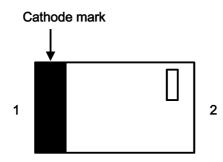


5. Electrical Characteristics (Note) (Unless otherwise specified, Ta = 25 °C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward voltage	V _F	I _F = 1 mA	_	0.24	_	V
Forward current	I _F	V _F = 0.5 V	2	_		mA
Reverse current	I _R	V _R = 0.5 V	_	_	25	μΑ
Total capacitance	Ct	V _R = 0.2 V, f = 1 MHz	_	0.25		pF

Note: Signal level for capacitance measurement: Vsig = 20 mVrms

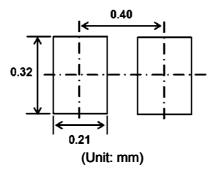
6. Marking



7. Usage Considerations

Schottky barrier diodes (SBDs) have reverse leakage greater than other types of diodes. This makes SBDs
more susceptible to thermal runaway under high-temperature and high-voltage conditions. Thus, both
forward and reverse power losses of SBDs should be considered for thermal and safety design.

8. Land Pattern Dimensions (for reference only)





9. Characteristics Curves (Note)

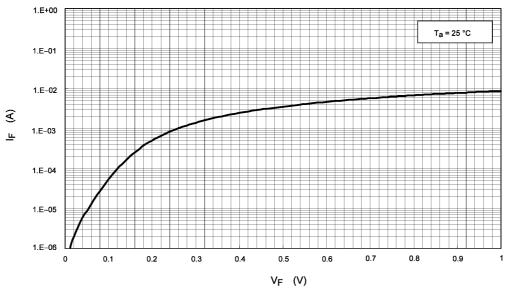


Fig. 9.1 I_F - V_F

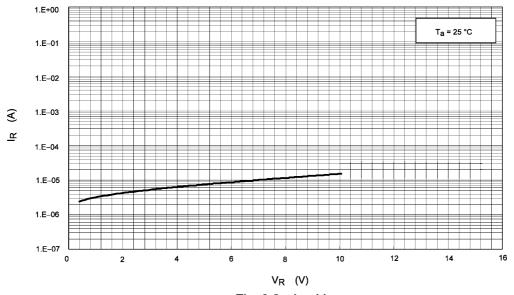
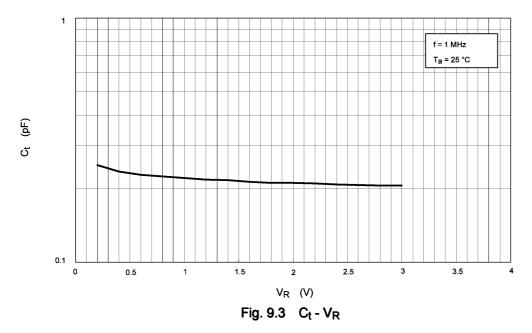


Fig. 9.2 I_R - V_R



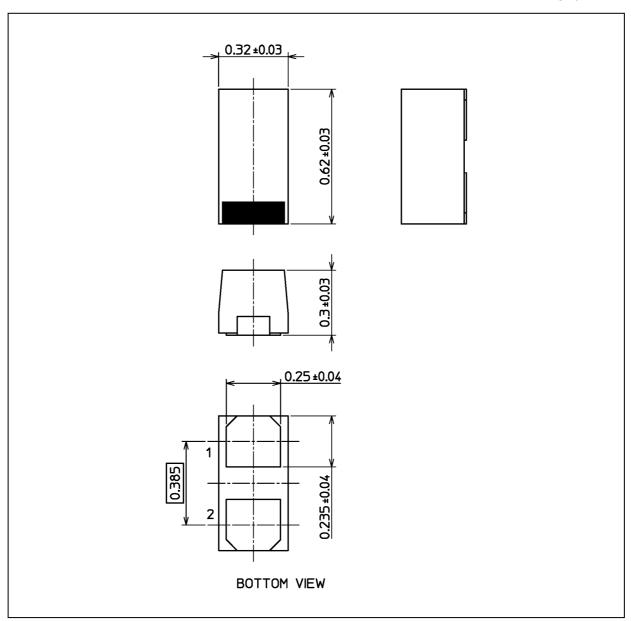
Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Rev.2.0



Package Dimensions

Unit: mm



Weight: 0.2 mg (typ.)

Package Name(s)
TOSHIBA: 1-1AL1A
Nickname: SL2



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